

# MA110

## Silicon Epitaxial Planar Type

### Switching

#### ■ Features

- High density mounting by "S-Mini type" package is possible.
- Fast  $t_{rr}$
- Small  $C_i$

#### ■ Absolute Maximum Ratings (Ta=25°C)

Item	Symbol	Value	Unit
Reverse Voltage (DC)	$V_R$	40	V
Peak Reverse Voltage	$V_{RM}$	40	V
Average Forward Current	$I_{F(AV)}$	100	mA
Peak Forward Current	$I_{FM}$	225	mA
Non-Repetitive Peak Forward Surge Current	$I_{FSM}^*$	500	mA
Junction Temperature	$T_j$	150	°C
Storage Temperature	$T_{stg}$	-55 ~ +150	°C

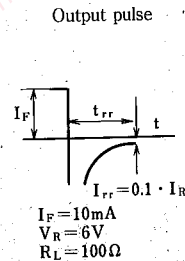
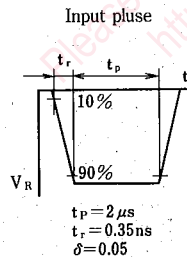
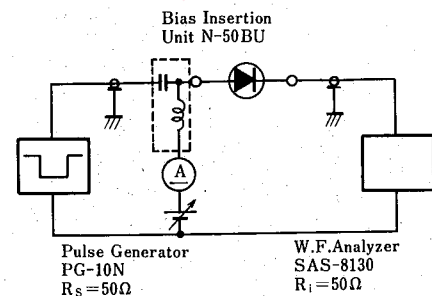
\* $t=1s$

#### ■ Electrical Characteristics (Ta=25°C)

Item	Symbol	Condition	min.	typ.	max.	Unit
Reverse Current (DC)	$I_R$	$V_R=35V$			100	nA
Forward Voltage (DC)	$V_F$	$I_F=100mA$		0.95	1.2	V
Reverse Voltage (DC)	$V_R$	$I_R=100\mu A$	40			V
Terminal Capacitance	$C_t$	$V_R=0, f=1MHz$		0.6	1.2	pF
Reverse Recovery Time	$t_{rr}^*$	$I_F=10mA, V_R=6V$ $I_{rr}=0.1 \cdot I_R, R_L=100\Omega$			3	ns

© Input and output frequency of ratings: 100MHz

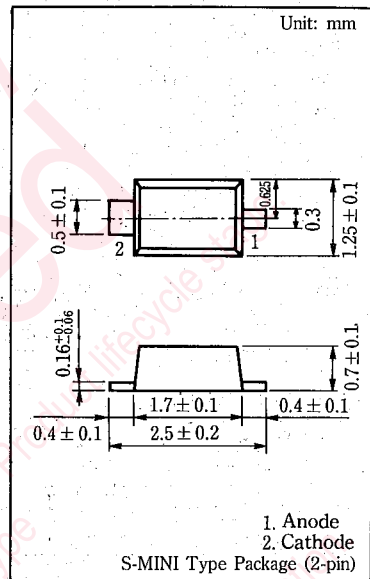
\* $t_{rr}$  measuring circuit



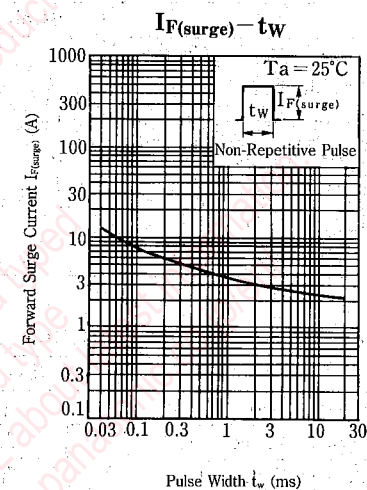
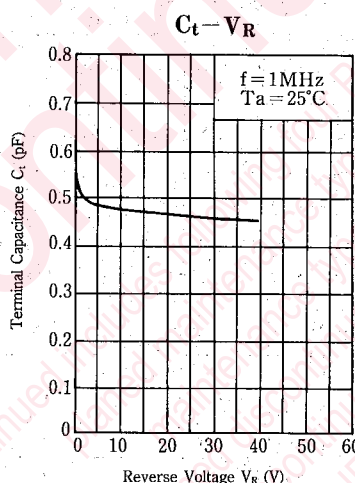
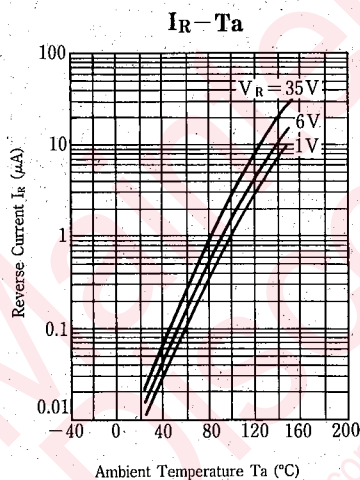
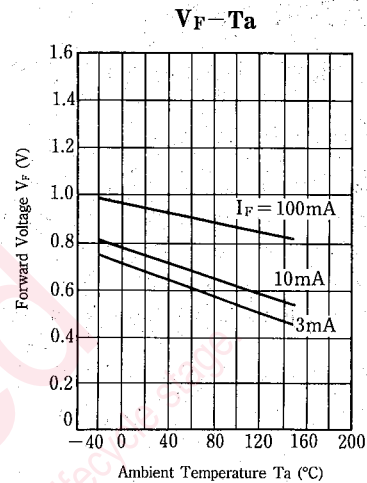
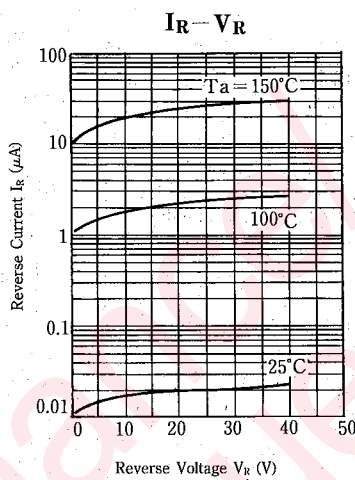
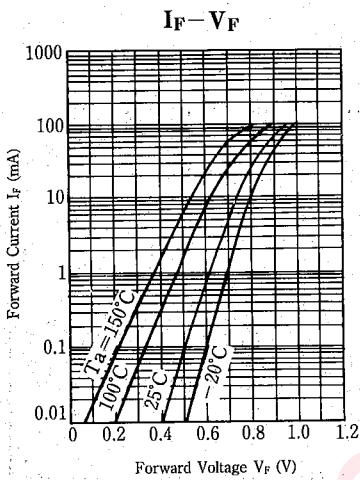
#### ■ Marking Symbol



#### ■ Package Dimensions



Marking Symbol : 1A



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